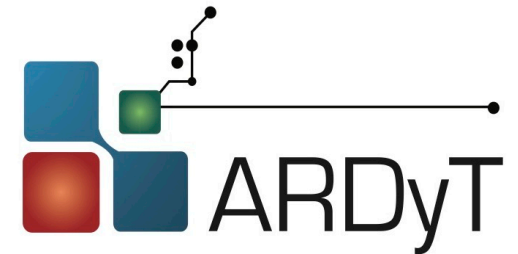


1

Projet ANR ARDyT



Architecture Reconfigurable dynamiquement
Tolérante aux fautes

Sébastien Pillement – IETR SCN



Réunion ISIS – 2 juillet 2013



Plan

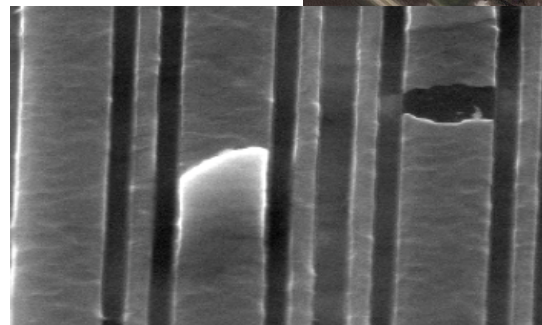
2

- Introduction et contexte
- Approche architecturale
 - ▣ Protection des ressources de bases
 - ▣ Protection des blocs arithmétique
 - ▣ Protection du bitstream
- Approche système
 - ▣ Gestion dynamique
- Approche niveau outils
- Conclusion

Conjonction de deux phénomènes

3

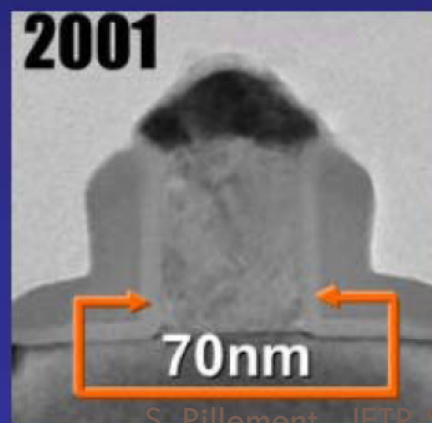
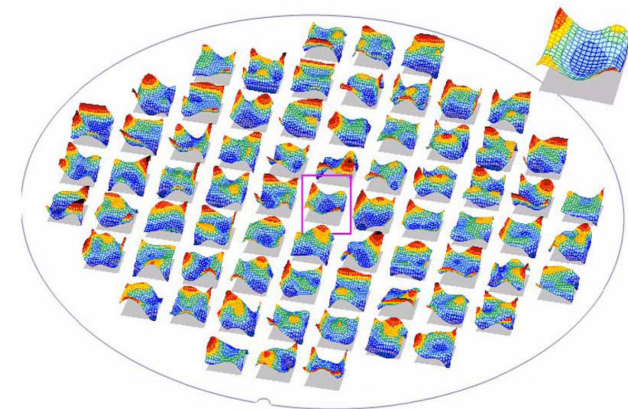
- de plus en plus de systèmes sont critiques.
 - ▣ Espace, Aviation, médical, automobile,
 - ▣ Banque, militaire,
 - ▣ Contrôle commande, ...
- Evolution technologique
 - ▣ Technologies nanométriques
 - ▣ Erreurs permanentes
 - ▣ Erreurs transitoires



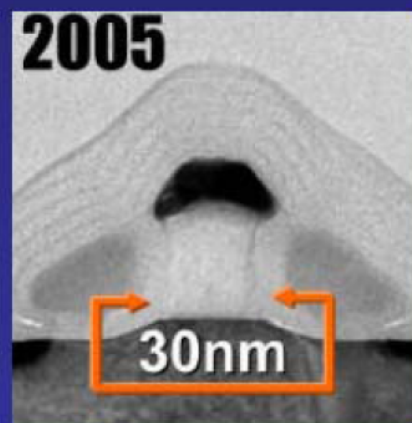
Erreurs permanentes

4

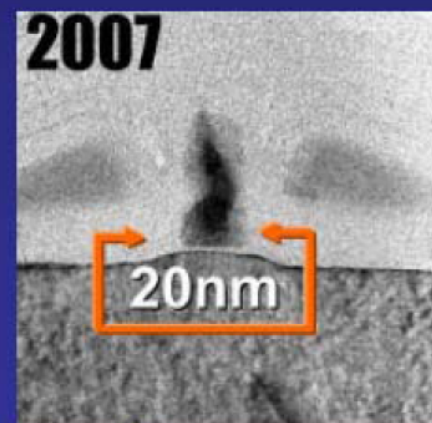
- ❑ Défauts de fabrication
- ❑ Dispersion des paramètres
- ❑ Vieillissements
- ❑ Stress électrique



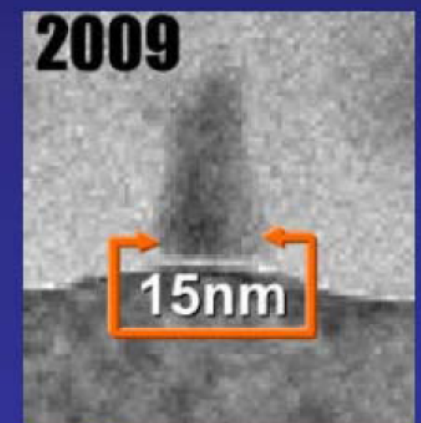
S. Pillement - IETR-3CN
0.13u process



65nm process



45nm process

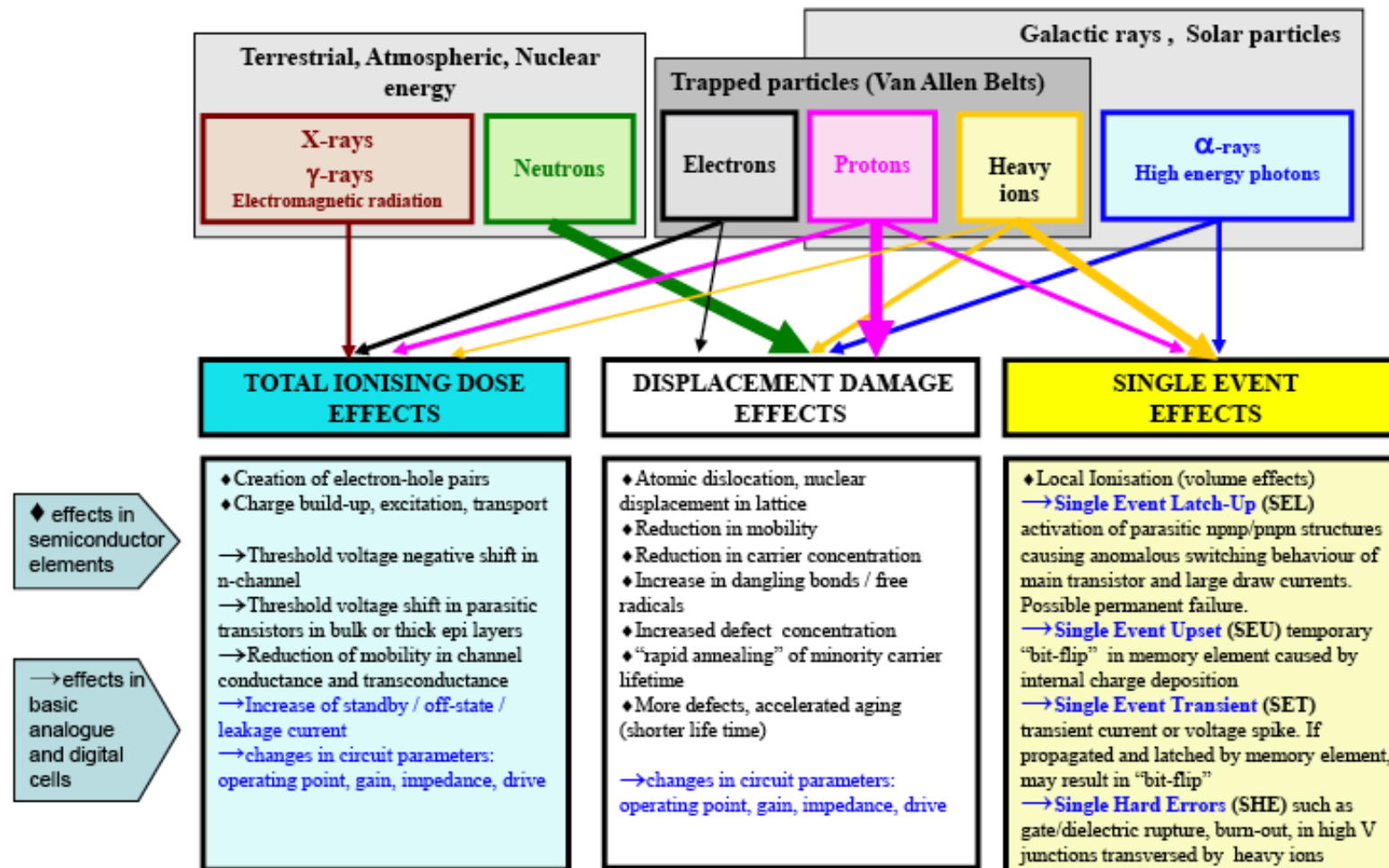


32nm process

Sources de radiations

5

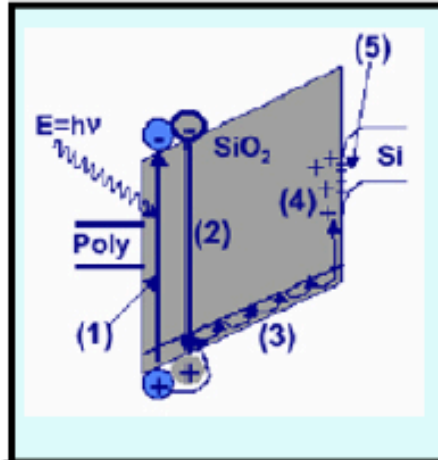
Radiation Effects in semiconductor devices



Impact des radiations

6

TOTAL IONISING DOSE EFFECTS



➤ POWER CONSUMPTION INCREASE

➤ DEGRADATION OF ANALOGUE FUNCTIONS / PERFORMANCE

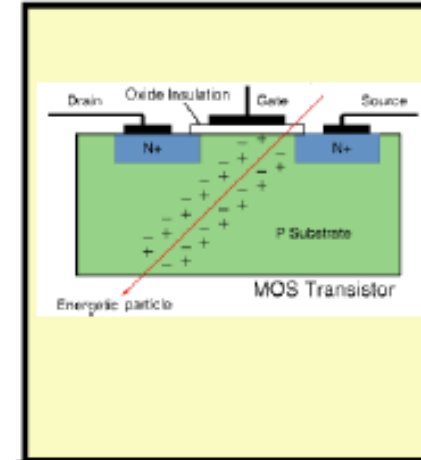
→ potential effects at ASIC or FPGA level

DISPLACEMENT DAMAGE EFFECTS

Typically this only concerns

electro-optic sensors,
diodes,
opto-couplers,
solar cells,
wide-base bipolar transistors

SINGLE EVENT EFFECTS



➤ TEMPORARY OR PERMANENT MALFUNCTION

➤ LOSS OF DATA

➤ POWER CONSUMPTION INCREASE

➤ DEVICE BURN OUT

Événements singuliers

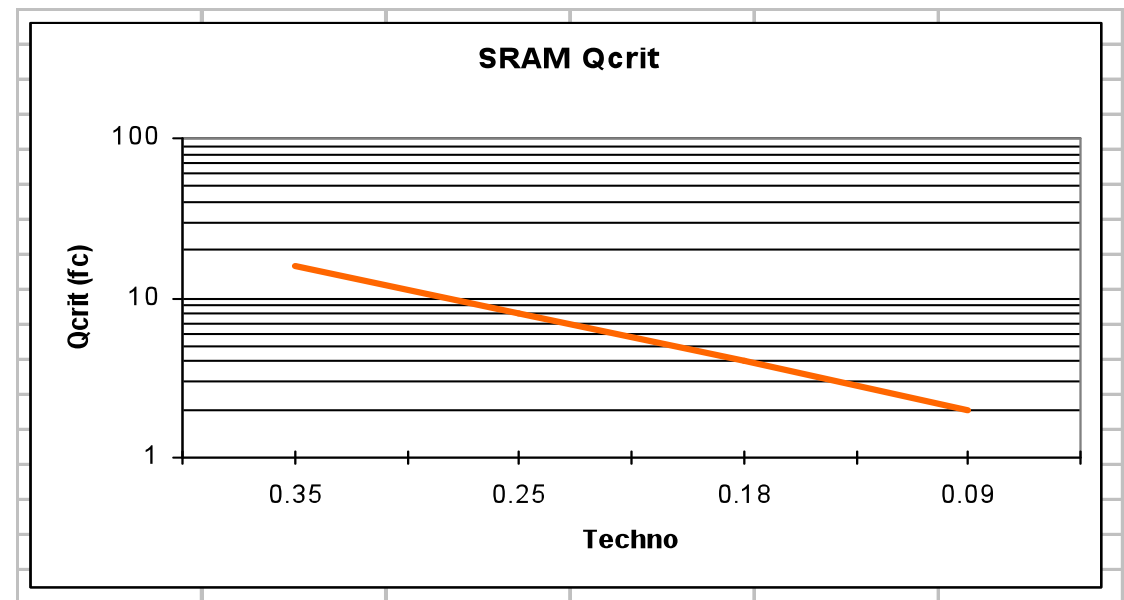
7

- Mise en route d'un transistor parasite PNP dans un MOSFET (SES - Single Event Snapback).
- Mise en conduction d'un thyristor parasite ou latch-up (SEL - Single Event Latch-up)
- Destruction du composant (SEB - Single Event Burn-out).
- Rupture de la grille des transistors MOS (SEGR - Single Event Gate Rupture)
- Basculement aléatoire d'une fonction bistable (SEU - Single Event Upset) Soft errors

Effet au sol

8

- Avec la réduction de la technologie, les radiations ionisantes deviennent un problème au sol
- Définitions :
 - ▣ Q_{crit} = charge critique = Niveau de charge nécessaire pour déclencher un événement
 - ▣ FIT = Taux d'erreurs (Failure in Time) = Fréquence d'erreurs causées par les radiations
 - 1 FIT = 1 erreur pendant 10^9 heures,
 - 1000 FIT = 1 erreur sur 114 ans



Effet sur des mémoires

9

- Campagne de test sur 80 mémoires en technologie CMOS 0.13um (Dec 02)

Conditions	FIT/Mb Neutrons	FIT/Mb alpha Am241	TOTAL
Sea level	1300	2200	3500
Alt.1500 m	3000	2200	5500

- Mesures Alpha varient drastiquement en fonction du type de package
- Pour 128 Mo, 1 erreur tous les 14 jours au niveau de la mer

Field Programmable Gate Array (FPGA)

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“Field Programmable”

- Integrated Circuit(IC) designed to be configured by the customer .

Why do we need FPGA ?

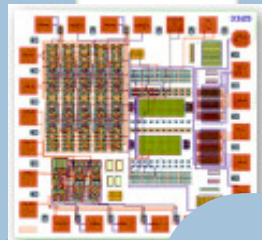
- ✓ Design Flexibility
- ✓ Partial Re-Configuration
- ✓ Low Non-Recurring Engineering Cost
- ✓ Fast Time to Market

The reconfiguration opportunities

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Self-repair

- overcome effects of threats & environment
- improve reliability lifetime
- graceful degradation



Reduce deployment time

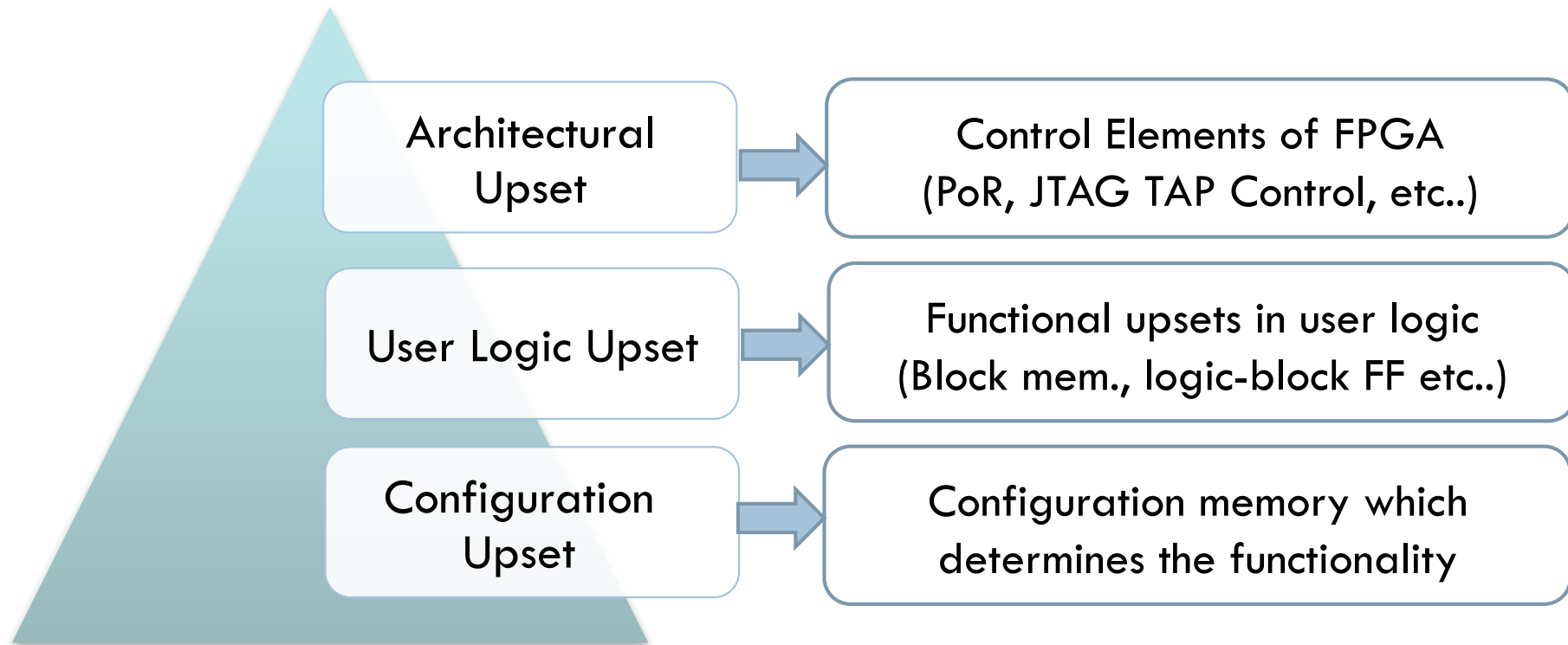
- adaptive interfaces to facilitate spacecraft integration
- reduce parts variety

Adapt to evolving threats, missions, & environments

- self-optimizing, high performance
- reconfigurable functionally
- redefinable power & data pathways

Upset Categories in FPGA

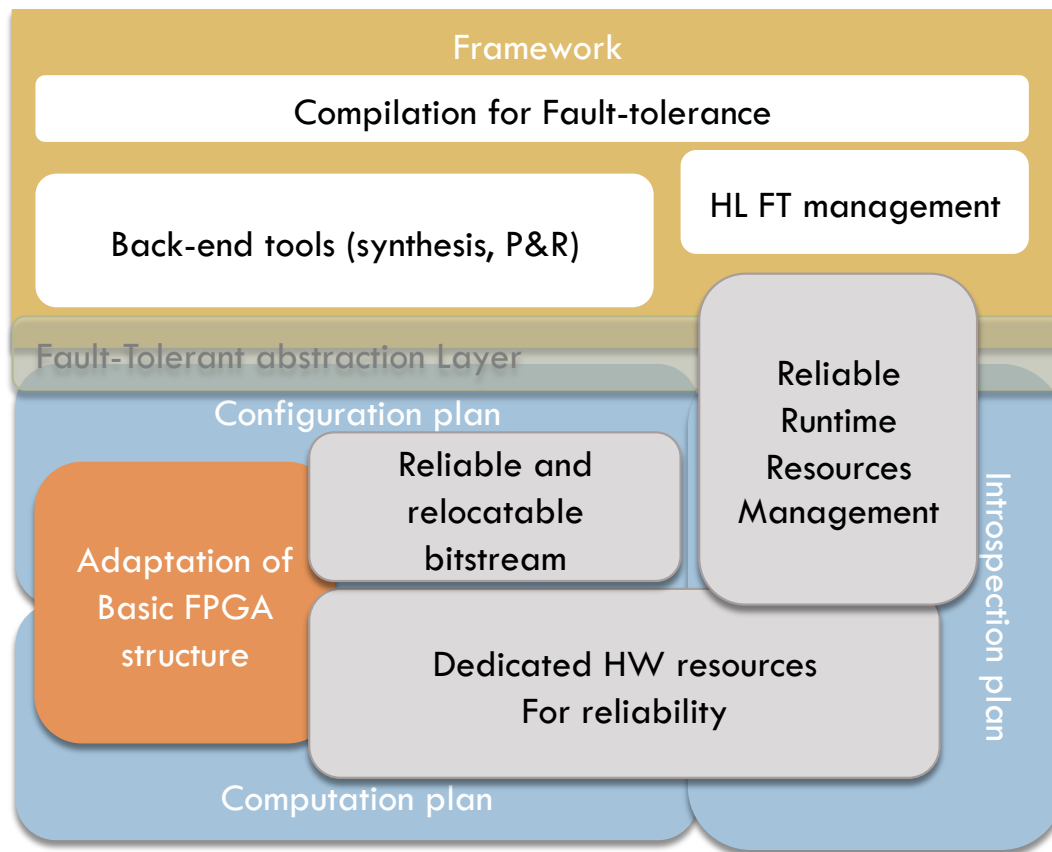
12



Hardened circuits at high costs and loss in performances

The ARDyT approach

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- Architecture
 - Basic FPGA blocks protection
 - Bitstream protection
 - Dynamicity support
- System
 - Dynamic management
- Tools
 - DFFT

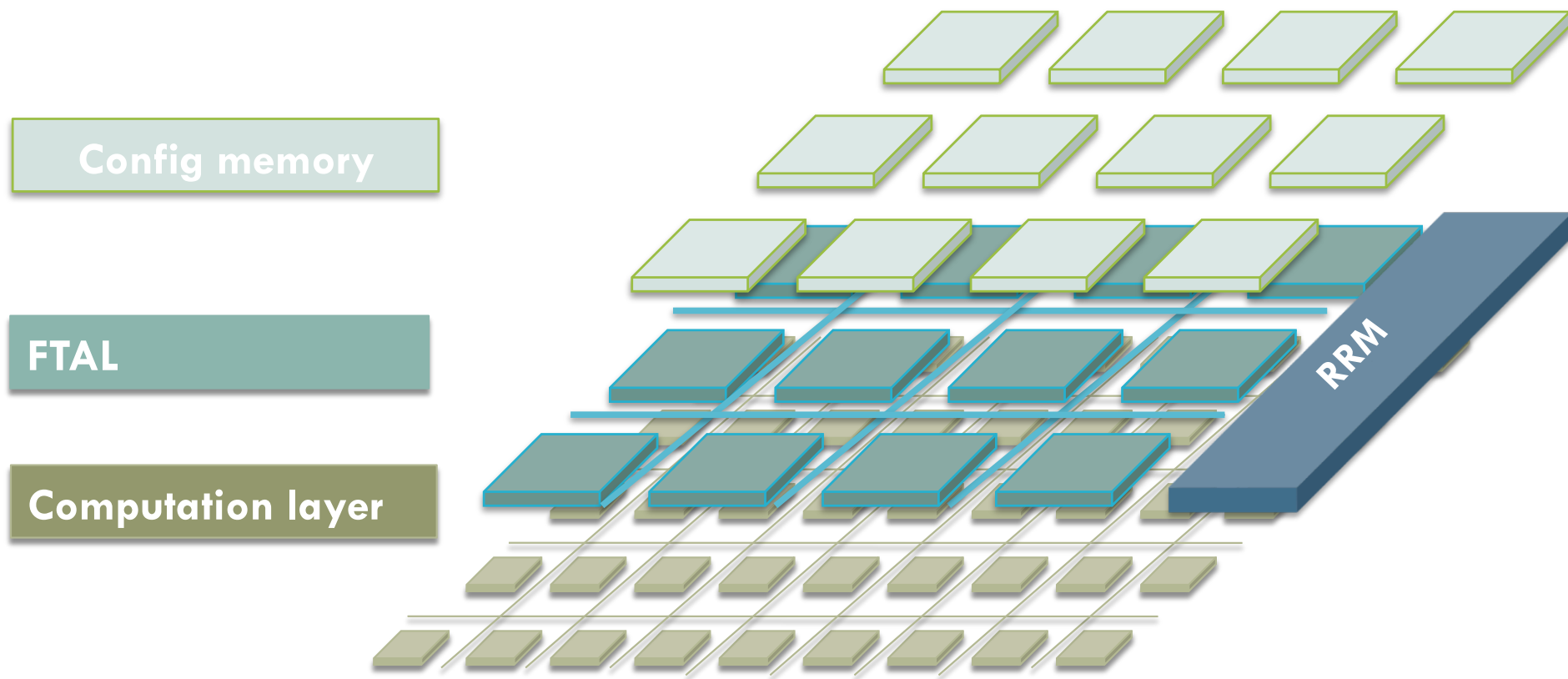
Plan

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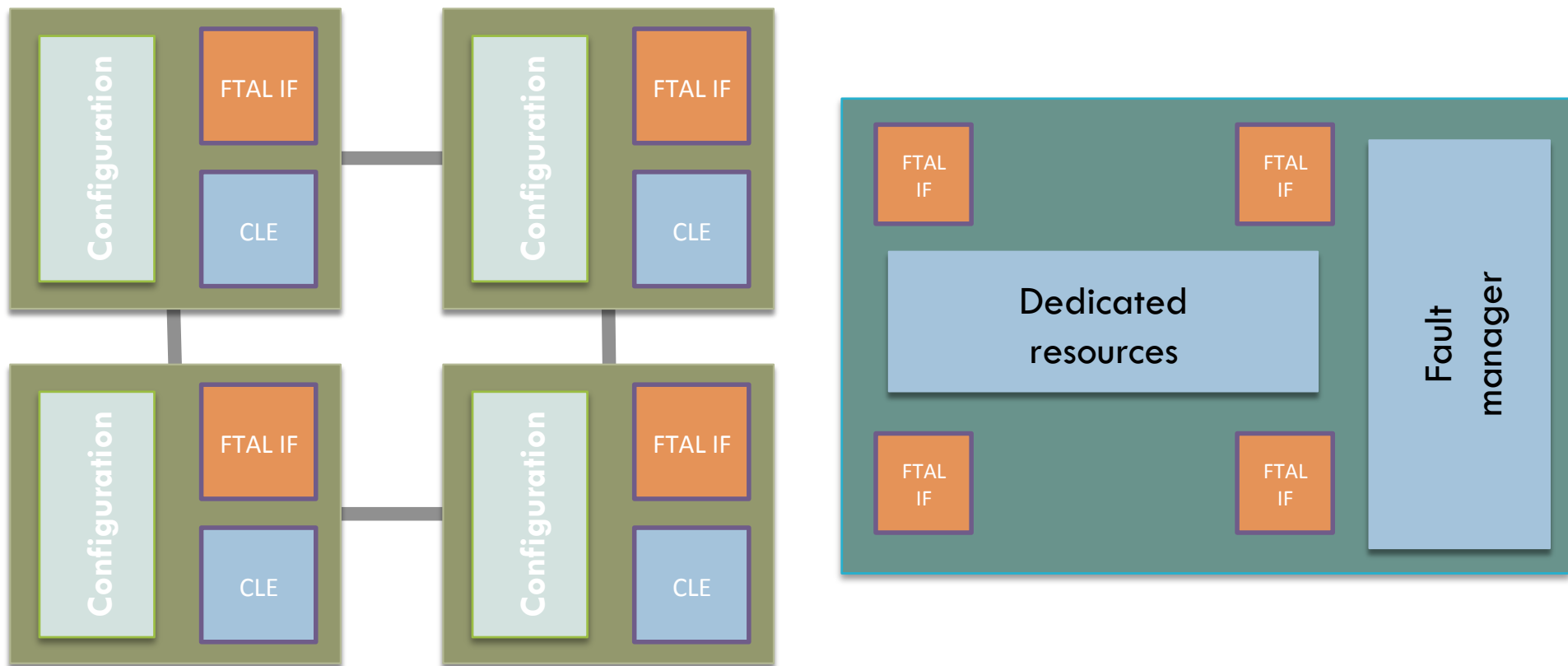
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System architecture

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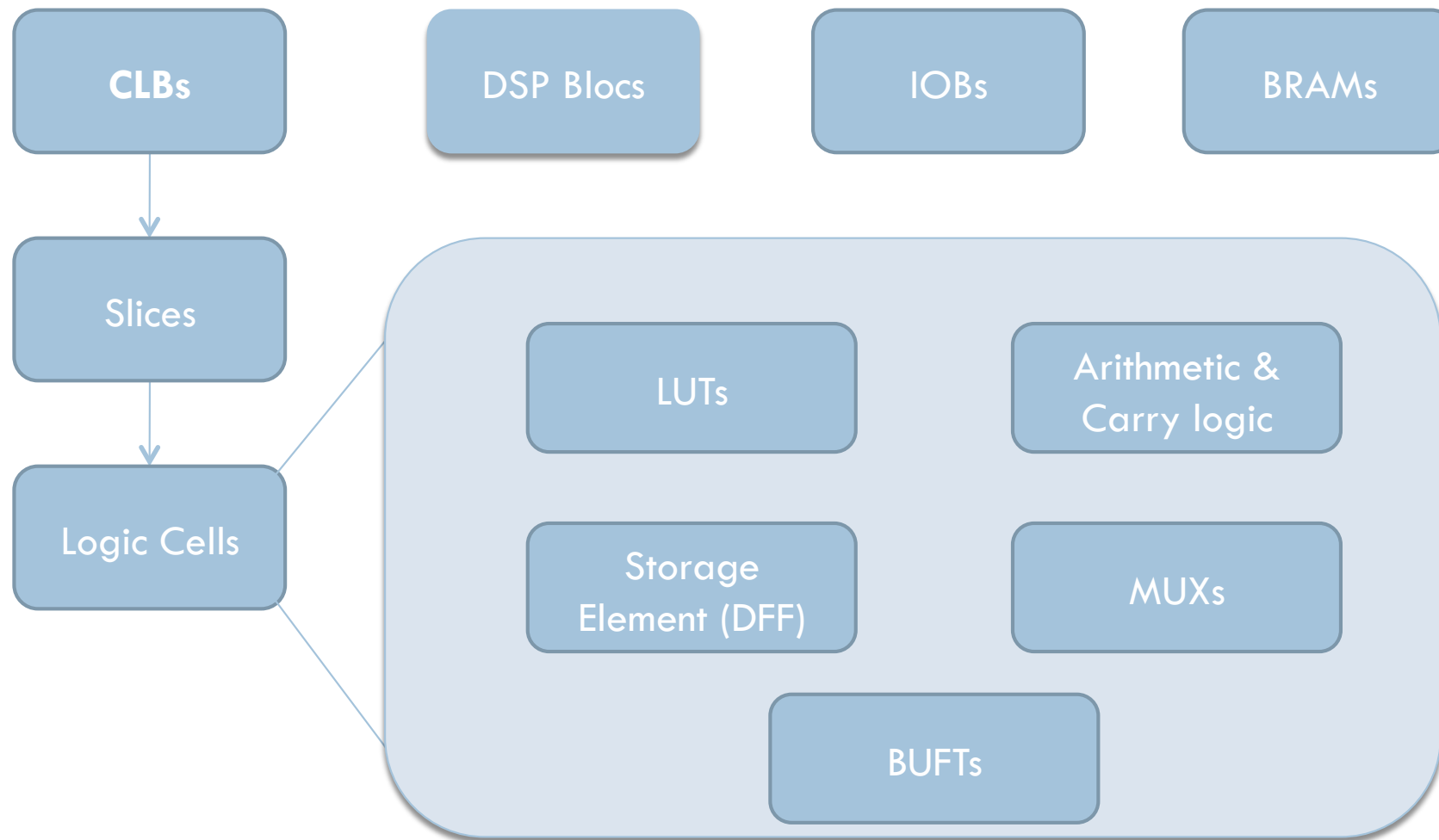


Architectural model



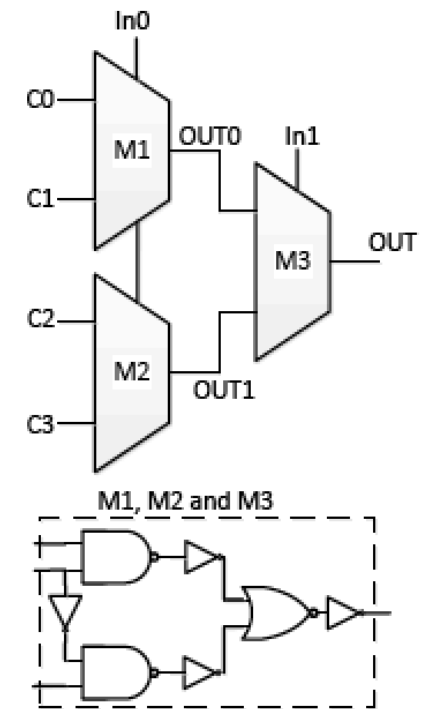
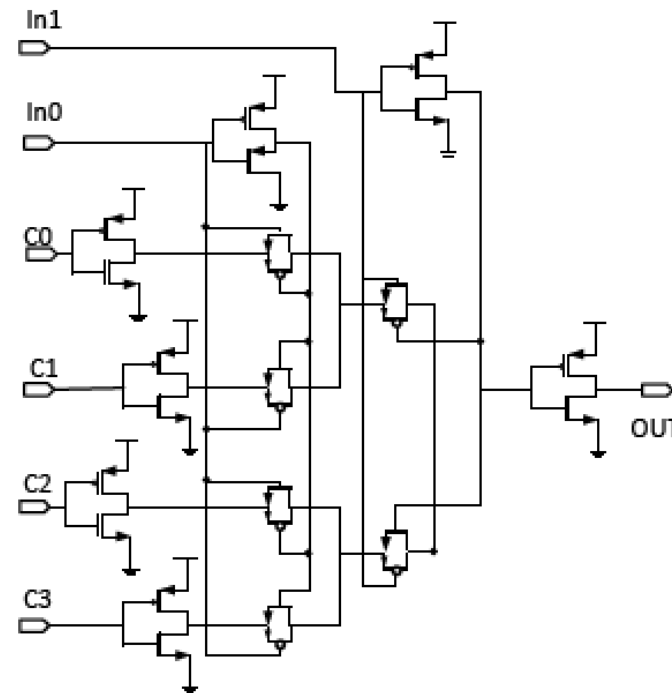
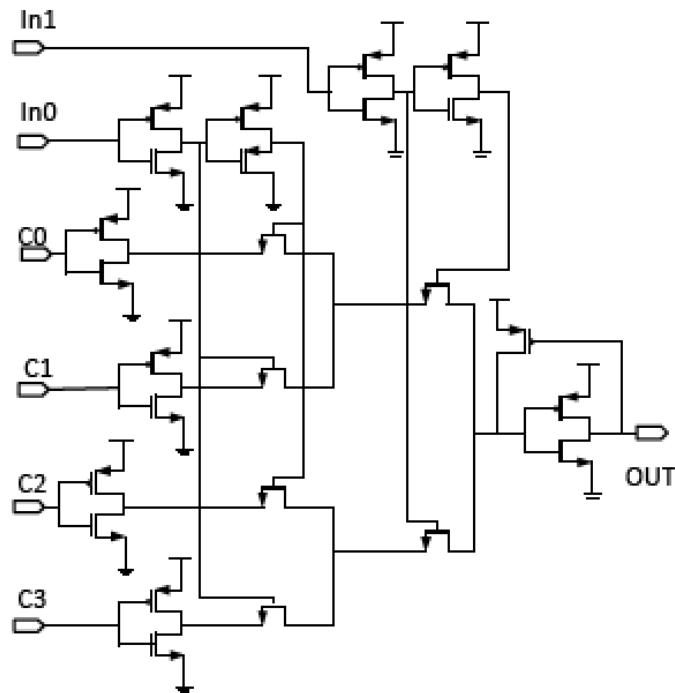
Types of CLE (Xilinx taxonomy)

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LUT protection

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- ❑ Most reliable structure?
- ❑ Wear-out mitigation by input swaping and « don't care » use.

DSP block protection

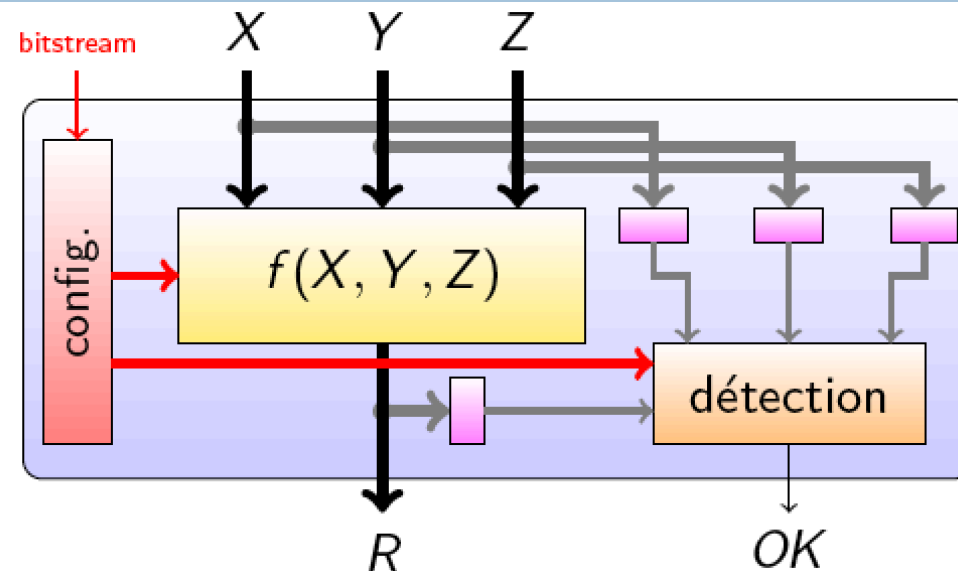
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Opérations supportées :

$$R \leftarrow X \cdot Y \pm Z$$

avec configurations :

- X, Y sur 8, 12, 16 bits
- Z sur 16, 24, 32, 40 bits
- signés / non-signés



Exemples résultats implantation ASIC 130 nm pour délai de 4 ns :

moduli	surface (μm^2)			puissance dyn. (μW)		
	comb.	reg.	total	cellules	noeuds	total
$\{2^6, 13, 15, 17\}$	12 068.9	10 983.7	23 052.6	1 734.9	293.4	2 028.3
$\{2^5, 13, 15, 31\}$	12 020.5	10 915.0	22 935.6	1 723.1	290.8	2 013.9
$\{2^3, 7, 13, 15, 17\}$	12 037.5	12 018.7	24 056.2	1 830.5	332.3	2 162.8
$\{2^2, 7, 13, 15, 31\}$	12 478.7	11 555.6	24 034.3	1 820.7	331.5	2 152.2
$\{2^2, 7, 15, 17, 31\}$	13 079.5	12 224.2	25 305.8	1 910.4	304.7	2 215.1

Configuration Memory Protection

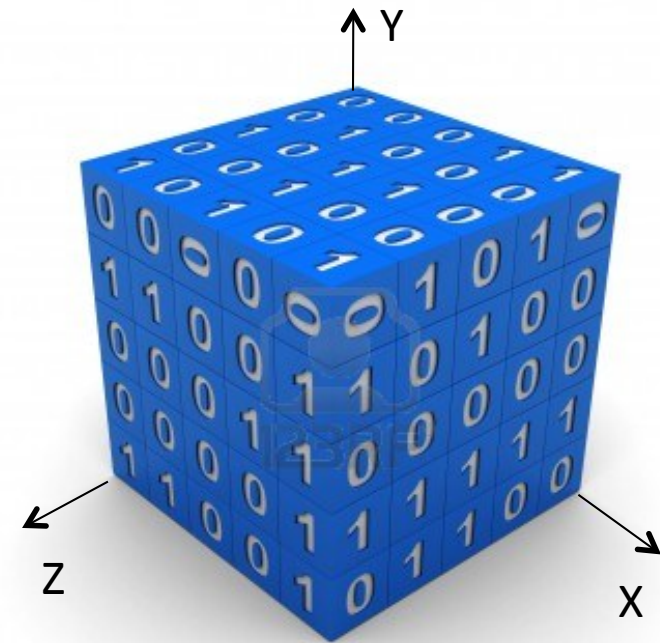
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3-Directional Hamming Scheme (3DH):

- A Built-in 3 Directional Hamming Error Correcting Mechanism is proposed.
- Mainly for Configuration memory protection.
- Doesn't need the backup copy (golden copy*) of whole configuration memory.
- Excessive access delay via IO ports is avoided.

Functionality:

- Information need to be protected is arranged in a memory platform.
- Hamming error correcting mechanism is applied to data words of the cube in all 3 directions (X, Y and Z).
- Maximum error bits are corrected.
- Multi-bit Upsets (MBUs) are easily cleared in this scheme.



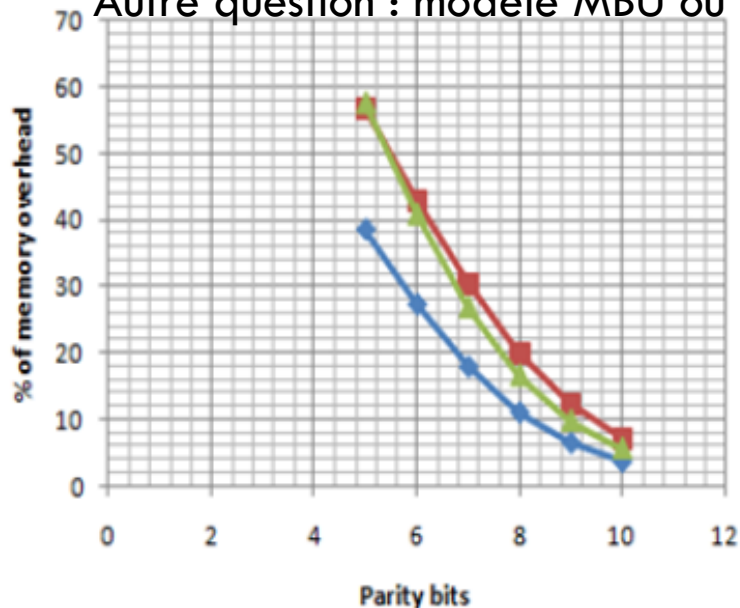
Requirements of 3DH:

21

- A virtual or physical 3D memory platform.
- Additional hardware or software to perform Hamming error correction on the 3D cube.
- Additional memory space to keep parity check bits of Hamming computation.
Question ici sur les conditions de mesures ? Combien d'erreurs ?? Pattern de fautes ?

Computational Results:

Autre question : modèle MBU ou SBU ? Bertrand à un article et une table excel d'évaluation from X
NON CORRECTABLE ERROR PATTERN COMPARISON



Window size	1DH scheme		2DH scheme		3DH Scheme	
	T_b	$\%N_{ep}$	T_b	$\%N_{ep}$	T_b	$\%N_{ep}$
3	3	0.5	9	0.1718	27	0.0086
4	4	0.6875	16	0.2368	64	0.0060

T_b - Total bits protected ; $\%N_{ep}$ - % of non correctable error patterns

- ◆ Conventional 1D Hamming
- Conventional 2D Hamming
- ▲ Proposed 3D Hamming

Comparison of parity memory overhead.

Plan

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Bitstream protection

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- Dynamic reconfiguration
 - ▣ Needs to support partial reconfiguration
- Relocatable bitstream
 - ▣ Enable task migration
- Bitstream encoding
 - ▣ Uses of adapted encoding
 - ▣ « Verifiable » bitstream

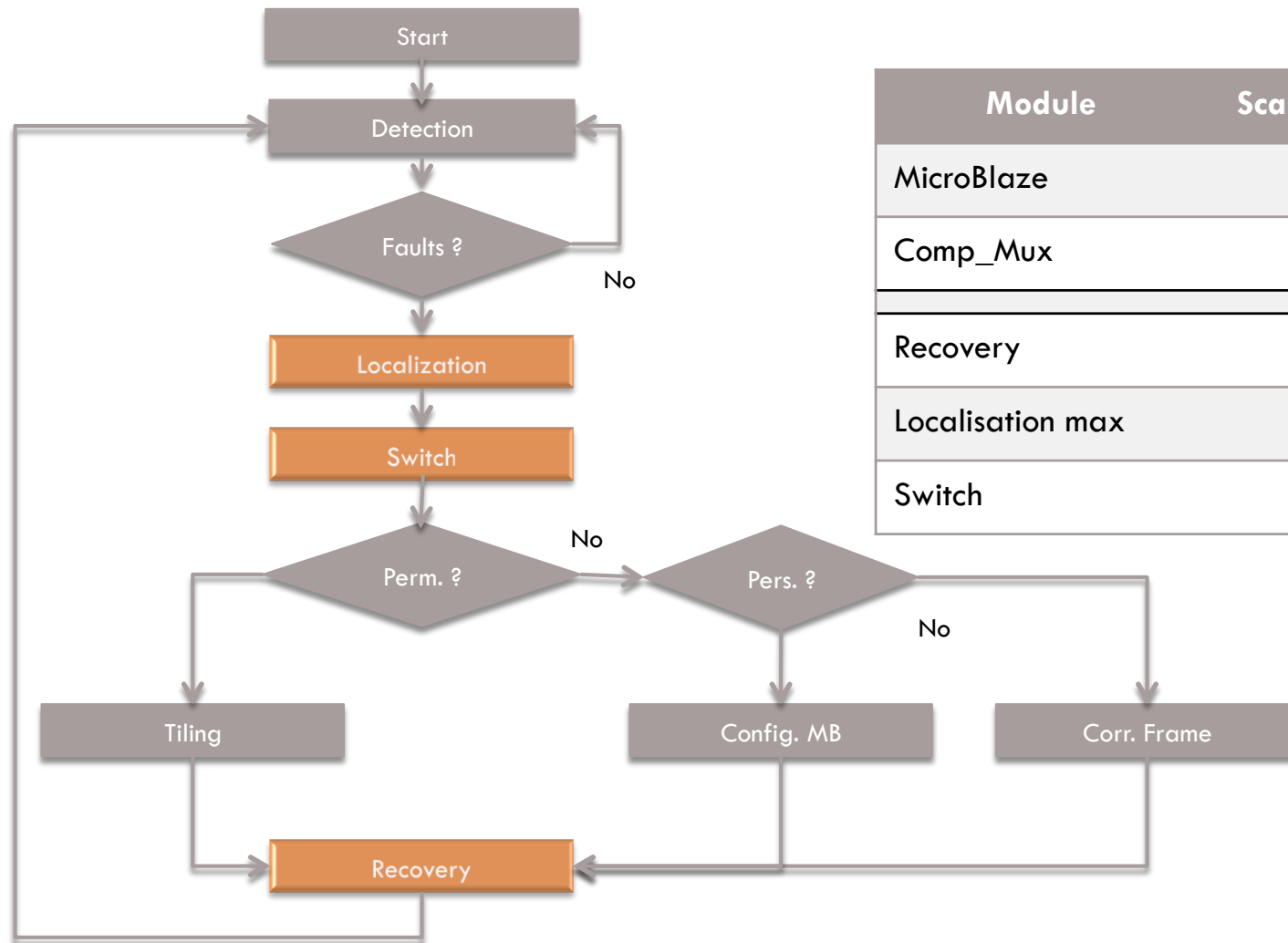
Runtime Reliable Manager

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- Dynamic reconfiguration capabilities
- Data-stream management capabilities
- Optimization of processing execution able to match functional requirements even under faulty conditions
- Efficient management system able to modify and adapt available FPGA resources (changing due to faults) during execution
- Based on fault detection mechanisms implemented in the hardware

Implement the fault mitigation strategy

Fault mitigation technique



Module	Scan time (μs)	Reconf time (μs)
MicroBlaze	270	326 000
Comp_Mux	25	185
Recovery	N/A	5,2
Localisation max	N/A	300
Switch	N/A	0,002

Plan

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- Introduction et contexte
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- **Approche niveau outils**
- **Conclusion**

Plan

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- Introduction et contexte
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 - ▣ Protection de la mémoire de config
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- **Conclusion**

Le projet ARDyT c'est ...

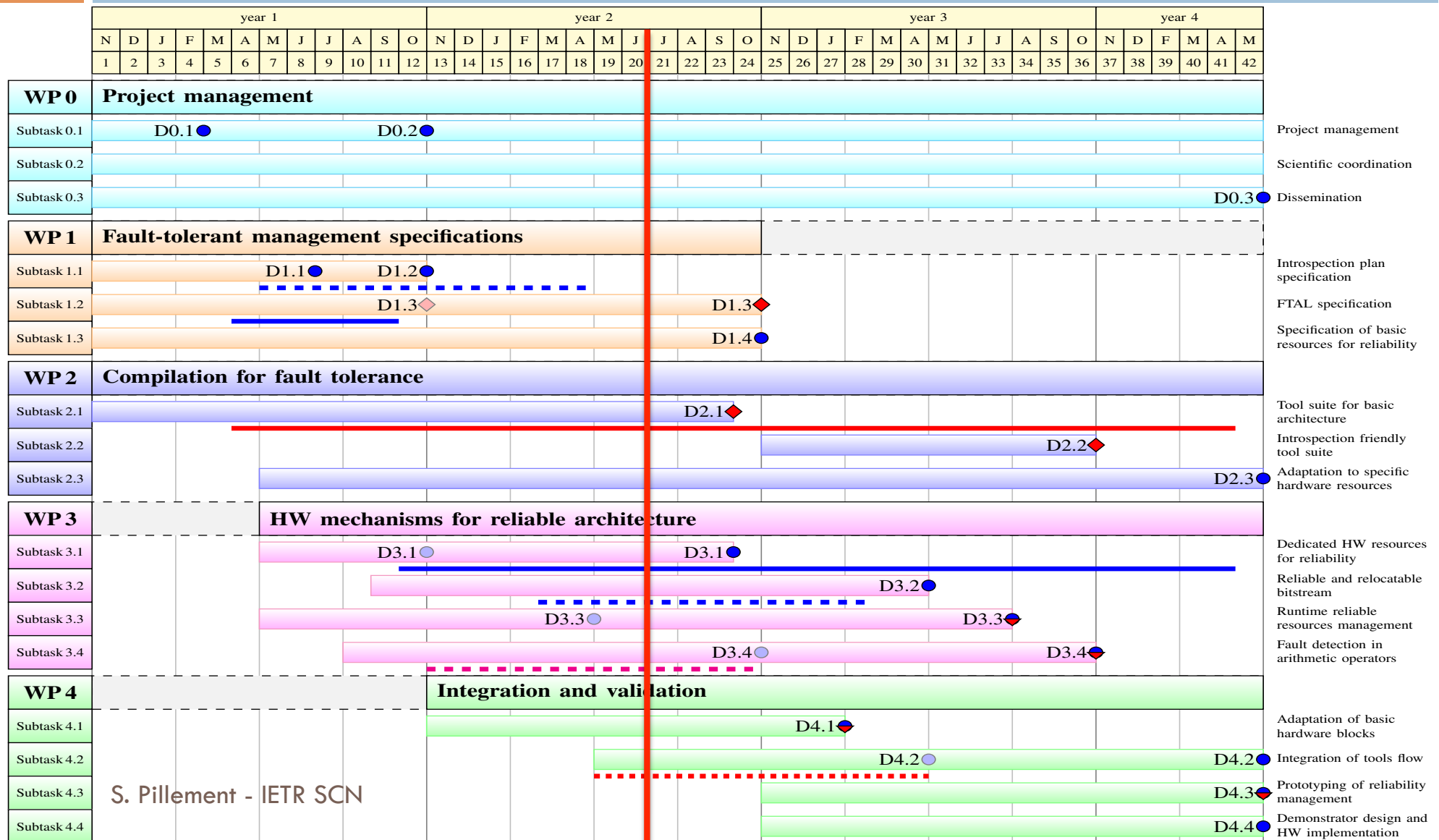
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Implémenter efficacement des applications dynamiques sur une architecture flexible, sûre et faible coût

- Principaux verrous
 - Structure matérielle « fiable »
 - Gestion dynamique de la fiabilité
 - Outils pour la fiabilité
- Innovations
 - Couche d'abstraction tolérante aux fautes
 - Gestion de la reconfiguration tolérante aux fautes
 - Approches arithmétiques et codage au niveau circuit
 - Synthèse pour la fiabilité sur le plan d'introspection
 - Tolérance aux fautes dynamique (self-healing)

Time schedule

30

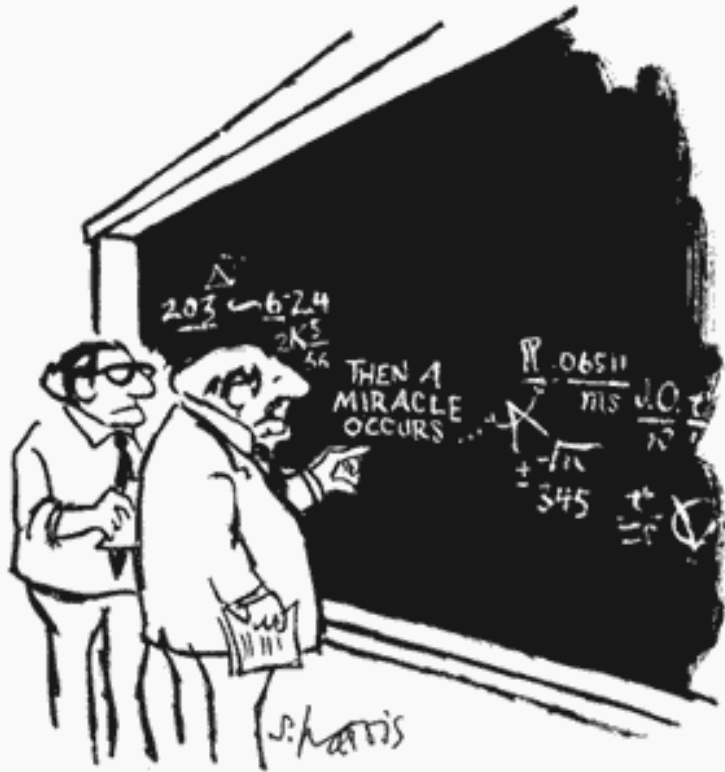


Final version: report ● source code ◆ report + source code ◆ Preliminary version: report ○ source code ◆

What's next

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- Architecture
 - Routing protection
 - User memories
 - DSE on DSP blocks
 - Use of exotic arithmetics
- System
 - Design of Reliable Ressources Manager
 - FTAL specification
- Tools
 - Design for Fault-tolerance
 - Introspection plan



"I THINK YOU SHOULD BE MORE EXPLICIT HERE IN STEP TWO."



Merci de votre attention.

Question ?

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